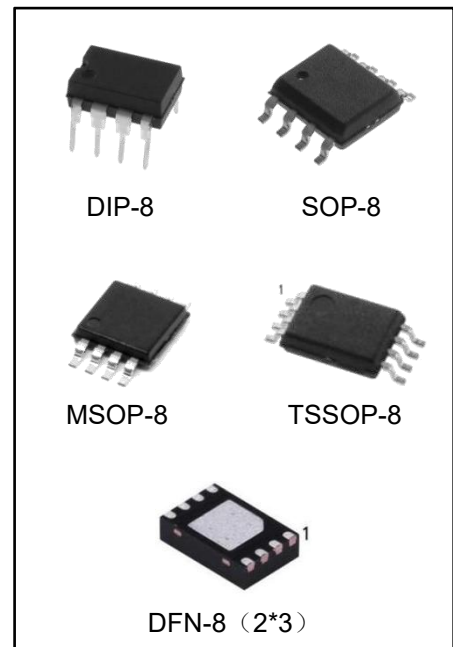


## 16K BITS EEPROM

### Features

- Compatible with all I2C bidirectional data transfer protocol
- Memory array:
  - 16K bits (2048 X 8) of EEPROM
  - Page size: 16 bytes
- Single supply voltage and high speed:1 MHz
- Random and sequential Read modes
- Write:
  - Byte Write within 3 ms
  - Page Write within 3 ms
  - Partial Page Writes Allowed
- Write Protect Pin for Hardware Data Protection
- Schmitt Trigger, Filtered Inputs for Noise Suppression
- High-reliability
  - Endurance: 1 Million Write Cycles
  - Data Retention: 100 Years
- Enhanced ESD/Latch-up protection:HBM 8000V
- 8-lead DIP/SOP/TSSOP/MSOP and DFN-8 package



### Ordering Information

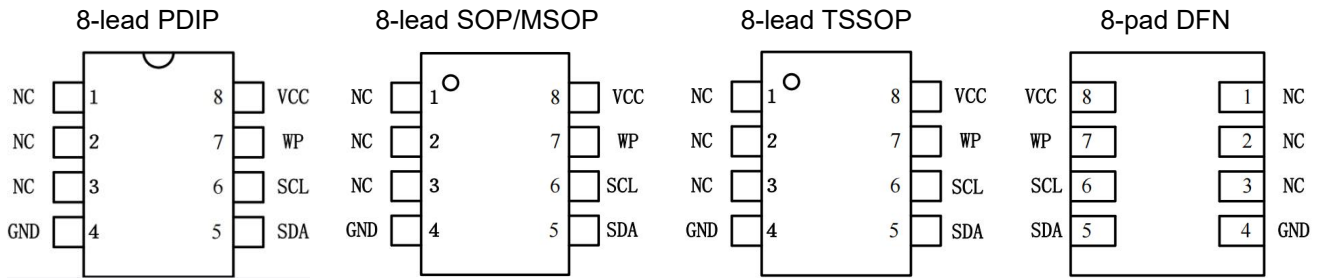
| DEVICE        | Package Type | MARKING | Packing | Packing Qty |
|---------------|--------------|---------|---------|-------------|
| AT24C16AN     | DIP-8        | 24C16A  | TUBE    | 2000/box    |
| AT24C16AM/TR  | SOP-8        | 24C16A  | REEL    | 2500/reel   |
| AT24C16AMM/TR | MSOP-8       | 24C16A  | REEL    | 3000/reel   |
| AT24C16AMT/TR | TSSOP-8      | 24C16A  | REEL    | 2500/reel   |
| AT24C16ADQ/TR | DFN-8 2*3    | C16A    | REEL    | 3000/reel   |

### Description

The AT24C16A provides 16384 bits of serial electrically erasable and programmable read-only memory (EEPROM), organized as 2048 words of 8 bits each.

The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential.

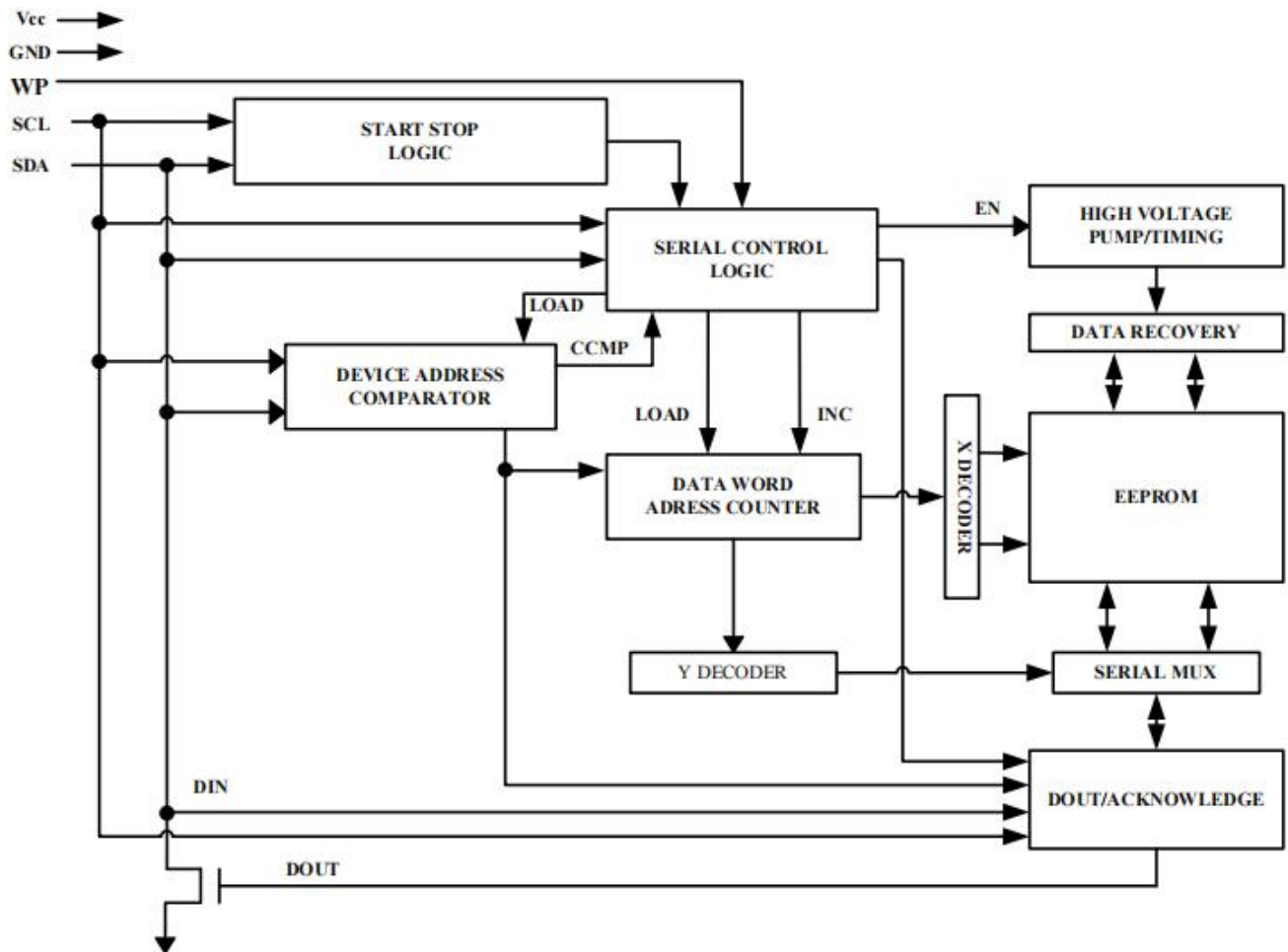
## Pin Configuration



## Pin Descriptions

| Pin Name | Type | Functions          |
|----------|------|--------------------|
| SDA      | I/O  | Serial Data        |
| SCL      | I    | Serial Clock Input |
| WP       | I    | Write Protect      |
| GND      | P    | Ground             |
| Vcc      | P    | Power Supply       |

## Block Diagram



**SERIAL DATA (SDA):** The SDA pin is bi-directional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or opencollector devices.

**SERIAL CLOCK (SCL):** The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.

**WRITE PROTECT (WP):** The AT24C16A has a Write Protect pin that provides hardware data protection. The Write Protect pin allows normal read/write operations when connected to ground (GND). When the Write Protection pin is connected to Vcc, the write protection feature is enabled and operates as shown in the following Table 2.

| WP Pin Status | AT24C16A                     |
|---------------|------------------------------|
| At VCC        | Full Array                   |
| At GND        | Normal Read/Write Operations |

## Functional Description

### 1.Memory Organization

**AT24C16A, 16K SERIAL EEPROM:** Internally organized with 128 pages of 16 bytes each, the 16K requires a 11-bit data word address for random word addressing.

### 2.Device Operation

**CLOCK and DATA TRANSITIONS:** The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods (see **Figure 2**). Data changes during SCL high periods will indicate a start or stop condition as defined below.

**START CONDITION:** A high-to-low transition of SDA with SCL high is a start condition which must precede any other command (see **Figure 3**).

**STOP CONDITION:** A low-to-high transition of SDA with SCL high is a stop condition. After a read sequence, the stop command will place the EEPROM in a standby power mode (see **Figure 3**).

**ACKNOWLEDGE:** All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a "0" to acknowledge that it has received each word. This happens during the ninth clock cycle.

**STANDBY MODE:** The AT24C16A features a low-power standby mode which is enabled: (a) upon power-up and (b) after the receipt of the STOP bit and the completion of any internal operations.

**MEMORY RESET:** After an interruption in protocol, power loss or system reset, any two-wire part can be reset by following these steps:

- 1、Clock up to 9 cycles.
- 2、Look for SDA high in each cycle while SCL is high.
- 3、Create a start condition.

Figure 2. Data Validity

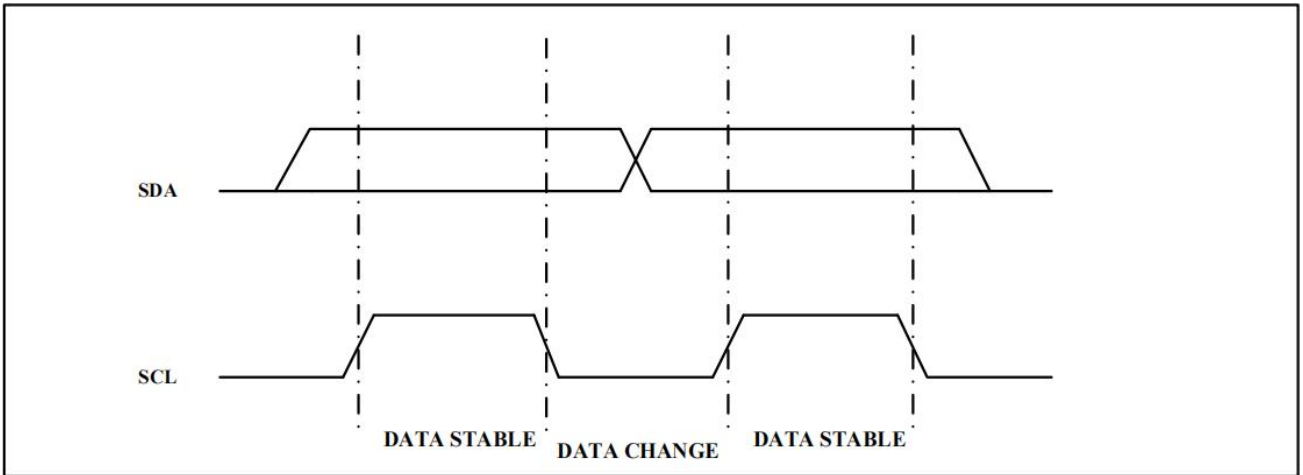


Figure 3. Start and Stop Definition

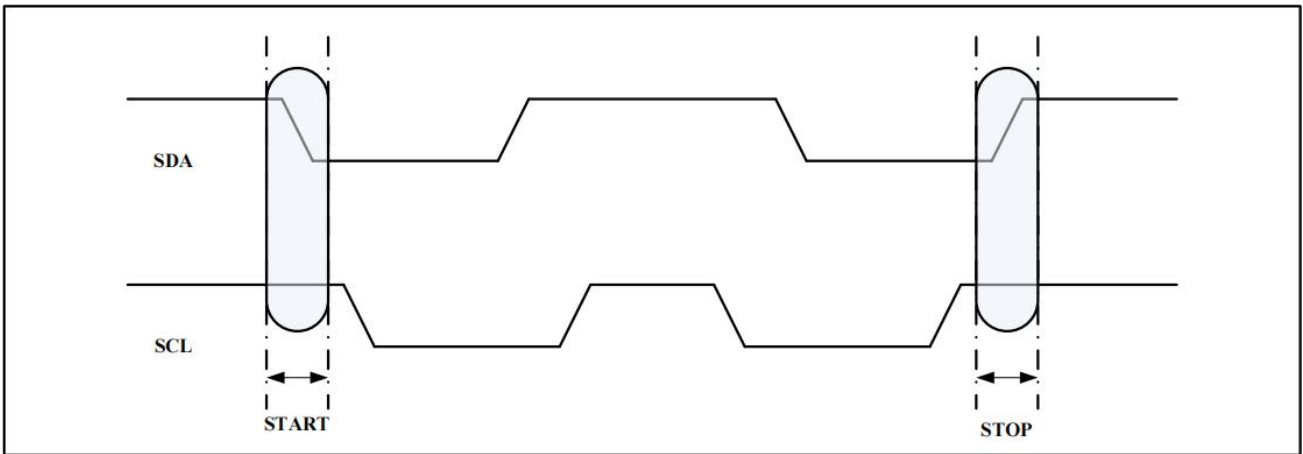
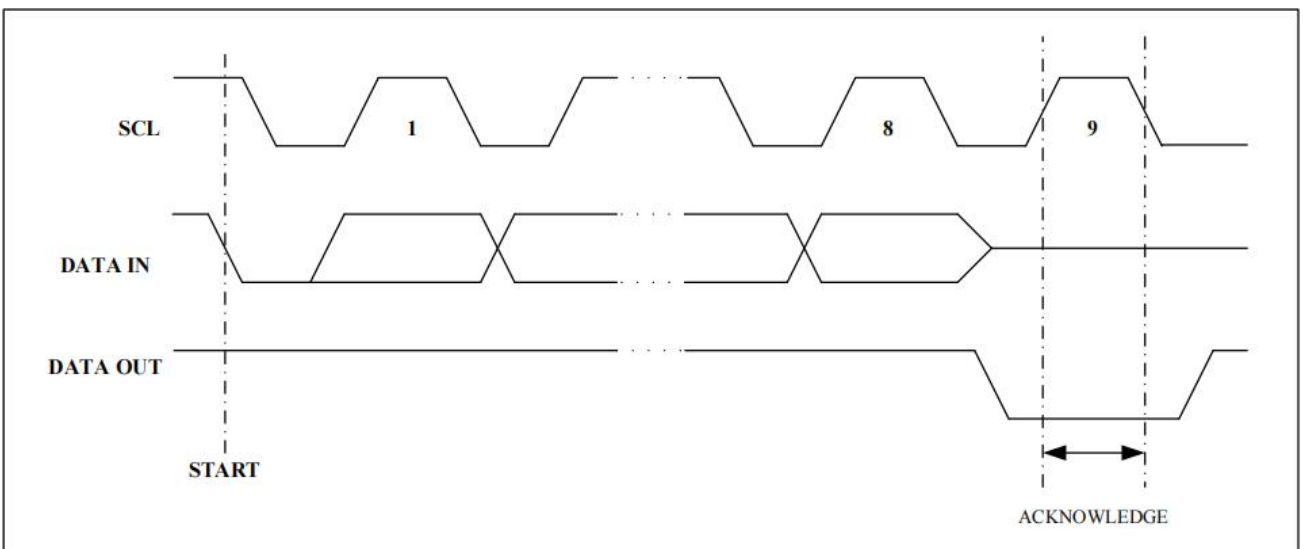


Figure 4. Output Acknowledge



### 3. Device Addressing

The AT24C16A EEPROM devices require an 8-bit device address word following a start condition to enable the chip for a read or write operation (see **Figure 5**)

The device address word consists of a mandatory "1", "0" sequence for the first four most significant bits as shown. This is common to all the Serial EEPROM devices.

The 16K does not use any device address bits but instead the 3 bits are used for memory page addressing. These page addressing bits on the 4K, 8K and 16K devices should be considered the most significant bits of the data word address which follows.

The eighth bit of the device address is the read/write operation select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

Upon a compare of the device address, the EEPROM will output a "0". If a compare is not made, the chip will return to a standby state.

### 4. Write Operations

**BYTE WRITE:** A write operation requires an 8-bit data word address following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a "0" and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a "0" and the addressing device, such as a microcontroller, must terminate the write sequence with a stop condition. At this time the EEPROM enters an internally timed write cycle,  $t_{WR}$ , to the nonvolatile memory. All inputs are disabled during this write cycle and the EEPROM will not respond until the write is complete (see **Figure 6**).

**PAGE WRITE:** The AT24C16A EEPROM devices are capable of 16-byte page writes. A page write is initiated the same as a byte write, but the microcontroller does not send a stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to fifteen (8K) more data words. The EEPROM will respond with a "0" after each data word received. The microcontroller must terminate the page write sequence with a stop condition (see **Figure 7**).

The data word address lower four (16K) bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than sixteen (16K) data words are transmitted to the EEPROM, the data word address will "roll over" and previous data will be overwritten.

**ACKNOWLEDGE POLLING:** Once the internally timed write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a start condition followed by the device address word. The read/write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a "0", allowing the read or write sequence to continue.

## 5. Read Operations

Read operations are initiated the same way as write operations with the exception that the read/write select bit in the device address word is set to "1". There are three read operations: current address read, random address read and sequential read.

**CURRENT ADDRESS READ:** The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address "roll over" during read is from the last byte of the last memory page to the first byte of the first page. The address "roll over" during write is from the last byte of the current page to the first byte of the same page. Once the device address with the read/write select bit set to "1" is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input "0" but does generate a following stop condition (see **Figure 8**).

**RANDOM READ:** A random read requires a "dummy" byte write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a current address read by sending a device address with the read/write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a "0" but does generate a following stop condition (see **Figure 9**)

**SEQUENTIAL READ:** Sequential reads are initiated by either a current address read or a random address read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address limit is reached, the data word address will "roll over" and the sequential read will continue. The sequential read operation is terminated when the microcontroller does not respond with a "0" but does generate a following stop condition (see **Figure 10**).

Figure 5. Device Address

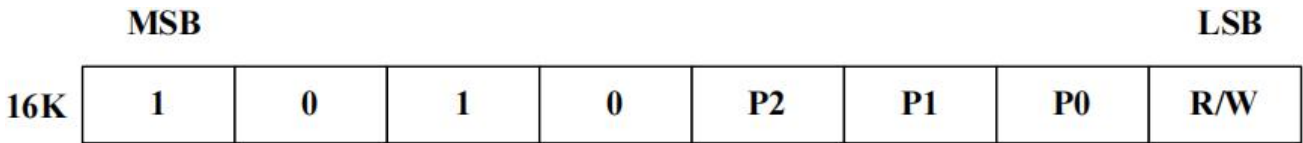


Figure 6. Byte Write

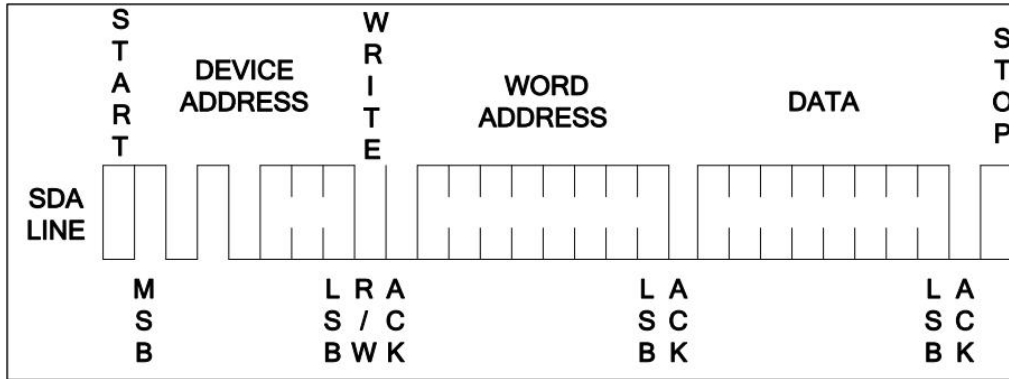


Figure 7. Page Write

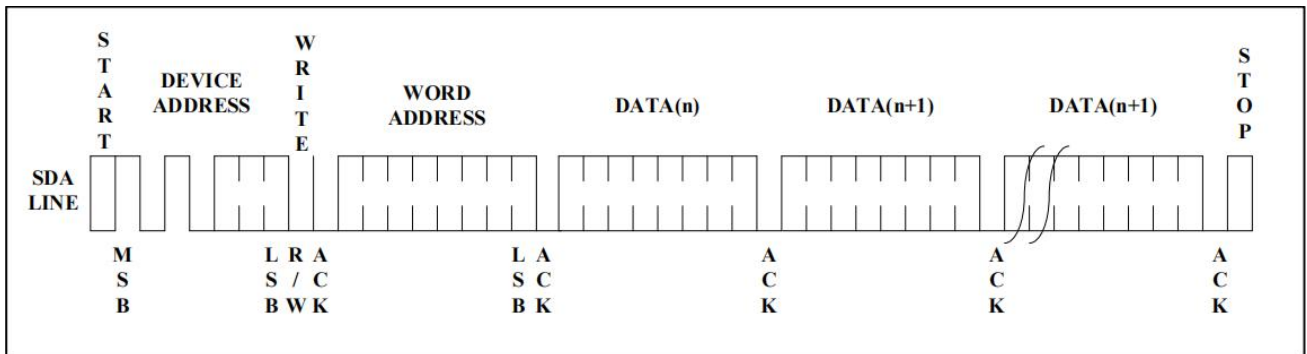
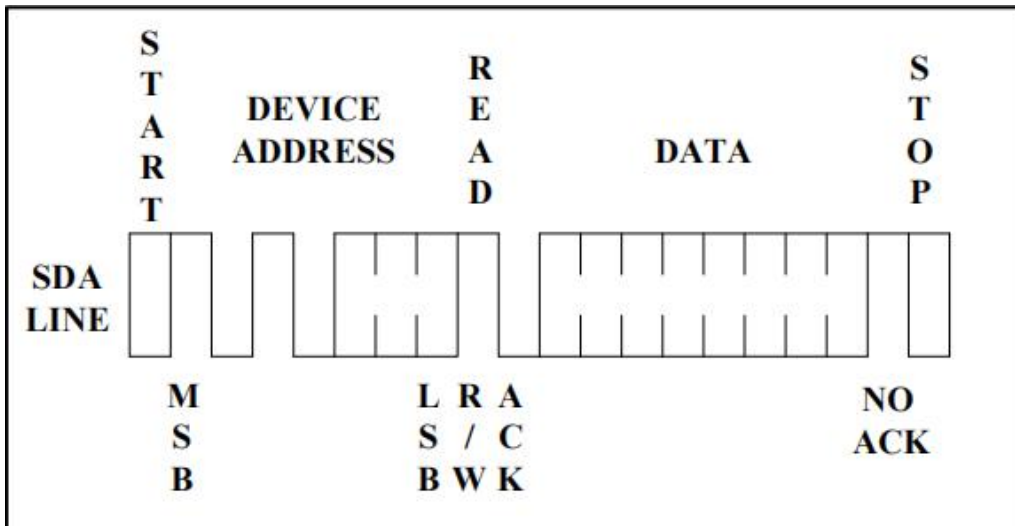
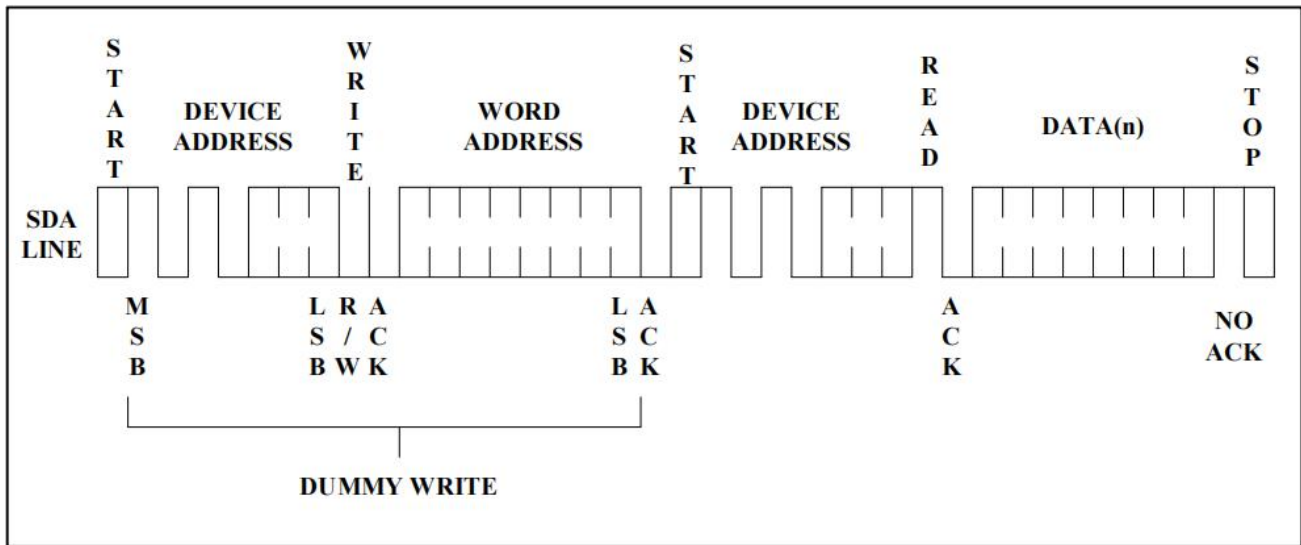
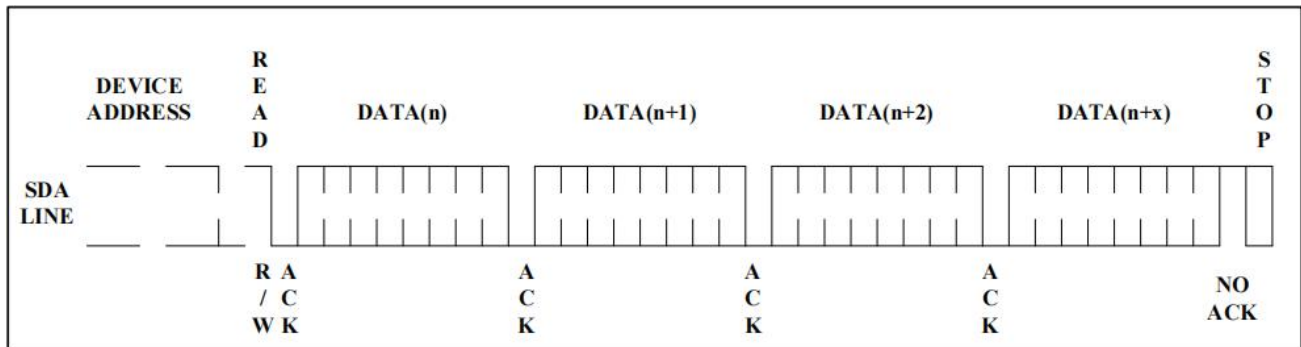


Figure 8. Current Address Read



**Figure 9. Random Read**

**Figure 10. Sequential Read**


## Electrical Characteristics

### Absolute Maximum Stress Ratings:

| Parameter                                | Limits               |
|--|----------------------|
| DC Supply Voltage                        | -0.3V to +6.5V       |
| Input / Output Voltage                   | GND-0.3V to VCC+0.3V |
| Operating Ambient Temperature            | -40°C to +85°C       |
| Storage Temperature                      | -65°C to +150°C      |
| Electrostatic pulse (Human Body model)   | 8000V                |
| Lead Temperature (Soldering, 10 seconds) | 245°C                |

### Comments:

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to this device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.



## DC Electrical Characteristics

Applicable over recommended operating range from: TA = -40°C to +85°C, VCC = +1.7V to +5.5V  
 (unless otherwise noted)

| Parameter                 | Symbol           | Min                  | Typ  | Max                  | Unit | Condition  |
|---------------------------|------------------|----------------------|------|----------------------|------|--|
| Supply Voltage            | V <sub>CC1</sub> | 1.7                  | -    | 5.5                  | V    | -  |
| Supply Voltage            | V <sub>CC2</sub> | 2.5                  | -    | 5.5                  | V    | -  |
| Supply Current VCC=5.0V   | I <sub>CC1</sub> | -                    | 0.14 | 0.3                  | mA   | READ at 400KHZ                                       |
| Supply Current VCC=5.0V   | I <sub>CC2</sub> | -                    | 0.28 | 0.5                  | mA   | WRITE at 400KHZ                                      |
| Supply Current VCC=5.0V   | I <sub>SB1</sub> | -                    | 0.03 | 0.5                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Input Leakage Current     | I <sub>L1</sub>  | -                    | 0.10 | 1.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Output Leakage Current    | I <sub>LO</sub>  | -                    | 0.05 | 1.0                  | μA   | V <sub>OUT</sub> =V <sub>CC</sub> or V <sub>SS</sub> |
| Input Low Level           | V <sub>IL1</sub> | -0.3                 | -    | V <sub>CC</sub> ×0.3 | V    | V <sub>CC</sub> =1.7V to 5.5V                        |
| Input High Level          | V <sub>IH1</sub> | V <sub>CC</sub> ×0.7 | -    | V <sub>CC</sub> +0.3 | V    | V <sub>CC</sub> =1.7V to 5.5V                        |
| Output Low Level VCC=1.7V | V <sub>OL1</sub> | -                    | -    | 0.2                  | V    | I <sub>OL</sub> =0.15mA                              |
| Output Low Level VCC=5.0V | V <sub>OL2</sub> | -                    | -    | 0.4                  | V    | I <sub>OL</sub> =3.0mA                               |

## Pin Capacitance

Applicable over recommended operating range from TA = 25°C, f = 1.0 MHz, VCC = +1.7V

| Parameter                     | Symbol           | Min | Typ | Max | Unit | Condition           |
|-------------------------------|------------------|-----|-----|-----|------|---------------------|
| Input/Output Capacitance(SDA) | C <sub>I/O</sub> | -   | -   | 8   | pF   | V <sub>IO</sub> =0V |
| Input Capacitance(SCL)        | C <sub>IN</sub>  | -   | -   | 6   | pF   | V <sub>IN</sub> =0V |

## AC Electrical Characteristics

Applicable over recommended operating range from TA = -40°C to +85°C, VCC = +1.7V to +5.5V, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

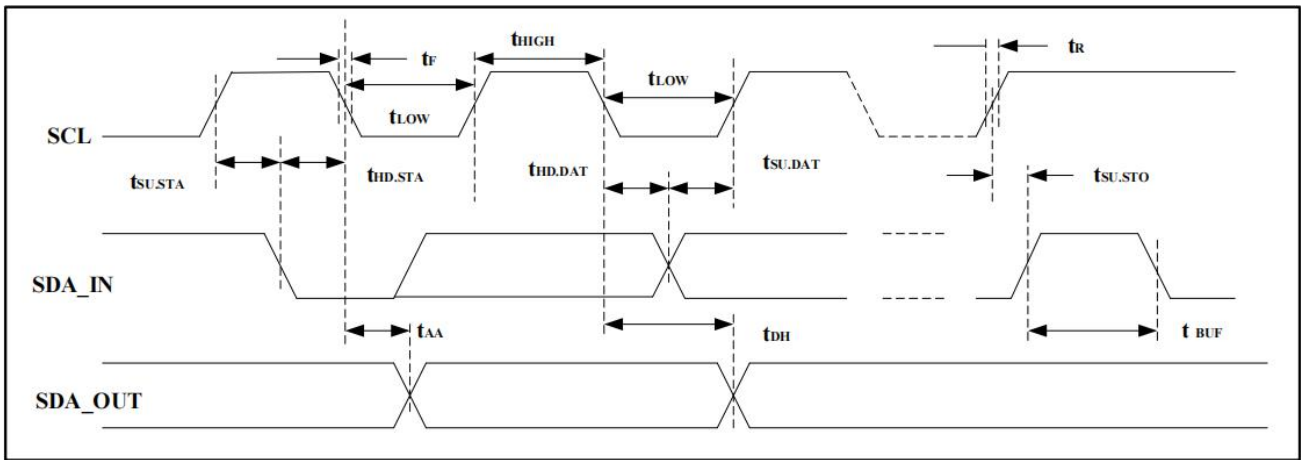
| Parameter  | Symbol              | 1.7V ≤ VCC < 2.5V |     |      | 2.5V ≤ VCC < 5.5V |     |      | Units       |
|--|---------------------|-------------------|-----|------|-------------------|-----|------|-------------|
|  |                     | Min               | Typ | Max  | Min               | Typ | Max  |             |
| Clock Frequency,SCL  | f <sub>SCL</sub>    | -                 | -   | 400  | -                 | -   | 1000 | KHZ         |
| Clock Pulse Width Low  | t <sub>LOW</sub>    | 0.6               | -   | -    | 0.6               | -   | -    | μs          |
| Clock Pulse Width High                                       | t <sub>HIGH</sub>   | 0.4               | -   | -    | 0.4               | -   | -    | μs          |
| Noise Suppression Time                                       | t <sub>I</sub>      | -                 | -   | 50   | -                 | -   | 50   | ns          |
| Clock Low to Data Out Valid                                  | t <sub>AA</sub>     | 0.1               | -   | 0.55 | 0.1               | -   | 0.55 | μs          |
| Time the bus must be free before anew transmission can start | t <sub>BUF</sub>    | 0.5               | -   | -    | 0.5               | -   | -    | μs          |
| Start Hold Time  | t <sub>HD:STA</sub> | 0.25              | -   | -    | 0.25              | -   | -    | μs          |
| Start Setup Time   | t <sub>SU:DAT</sub> | 0.25              | -   | -    | 0.25              | -   | -    | μs          |
| Data In Hold Time  | t <sub>HD:DAT</sub> | 0                 | -   | -    | 0                 | -   | -    | μs          |
| Data in Setup Time   | t <sub>SU:DAT</sub> | 100               | -   | -    | 100               | -   | -    | ns          |
| Input Rise Time(1)   | t <sub>R</sub>      | -                 | -   | 0.3  | -                 | -   | 0.3  | μs          |
| Input Fall Time(1)   | t <sub>F</sub>      | -                 | -   | 0.3  | -                 | -   | 0.3  | μs          |
| Stop Setup Time  | t <sub>SU:STO</sub> | 0.25              | -   | -    | 0.25              | -   | -    | μs          |
| Data Out Hold Time   | t <sub>DH</sub>     | 50                | -   | -    | 50                | -   | -    | ns          |
| Write Cycle Time   | t <sub>WR</sub>     | -                 | 1.9 | 3    | -                 | 1.9 | 3    | ms          |
| 5.0V,25°C,Byte Mode(1)                                       | Endurance           | 1M                | -   | -    | -                 | -   | -    | Write Cycle |

### Notes:

1. This parameter is characterized and is not 100% tested.
2. AC measurement conditions:  
 RL (connects to VCC): 1.3 k  
 Input pulse voltages: 0.3 VCC to 0.7 VCC Input rise and fall time: 50 ns  
 Input and output timing reference voltages: 0.5 VCC  
 The value of RL should be concerned according to the actual loading on the user's system.

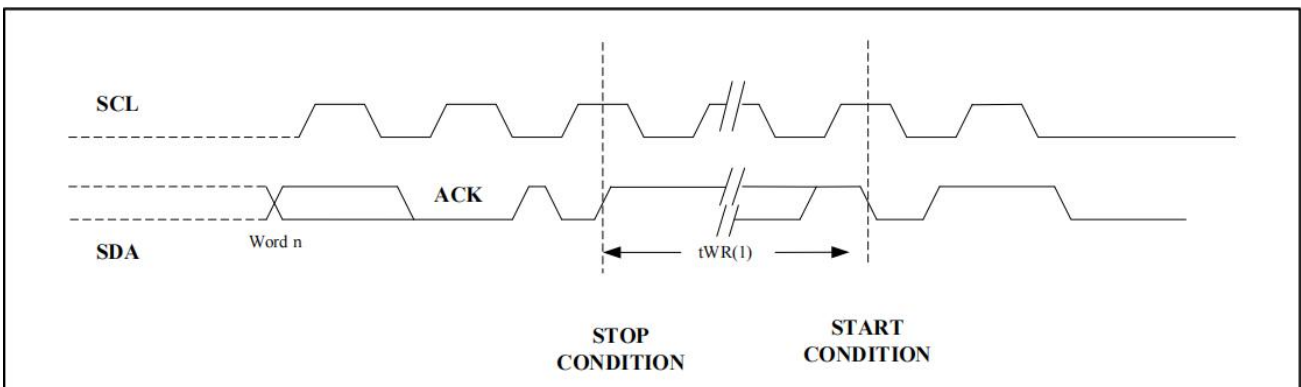
## Bus Timing

Figure 11. SCL: Serial Clock, SDA: Serial Data I/O



## Write Cycle Timing

Figure 12. SCL: Serial Clock, SDA: Serial Data I/O

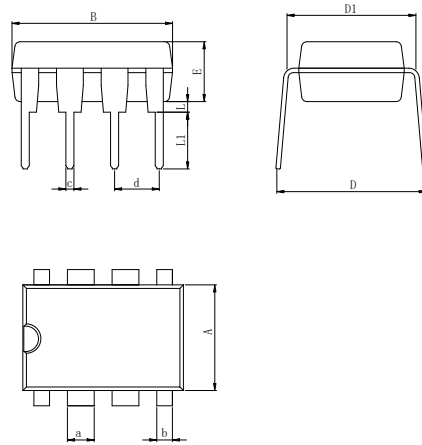


### Notes:

The write cycle time  $t_{WR}$  is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle.

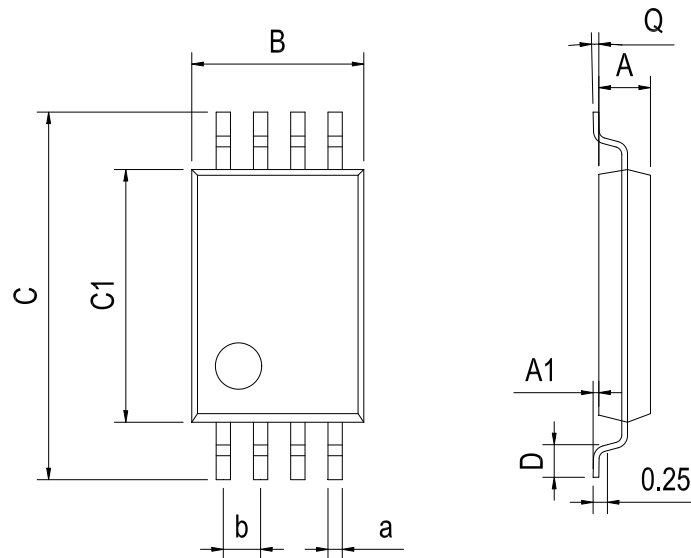
## Physical Dimensions

### DIP-8

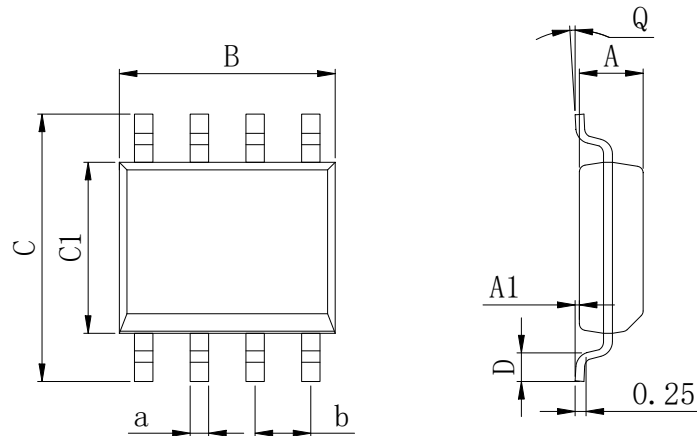


| Dimensions In Millimeters(DIP-8) |      |      |      |      |      |      |      |      |      |      |          |
|----------------------------------|------|------|------|------|------|------|------|------|------|------|----------|
| Symbol:                          | A    | B    | D    | D1   | E    | L    | L1   | a    | b    | c    | d        |
| Min:                             | 6.10 | 9.00 | 8.10 | 7.42 | 3.10 | 0.50 | 3.00 | 1.50 | 0.85 | 0.40 | 2.54 BSC |
| Max:                             | 6.68 | 9.50 | 10.9 | 7.82 | 3.55 | 0.70 | 3.60 | 1.55 | 0.90 | 0.50 |          |

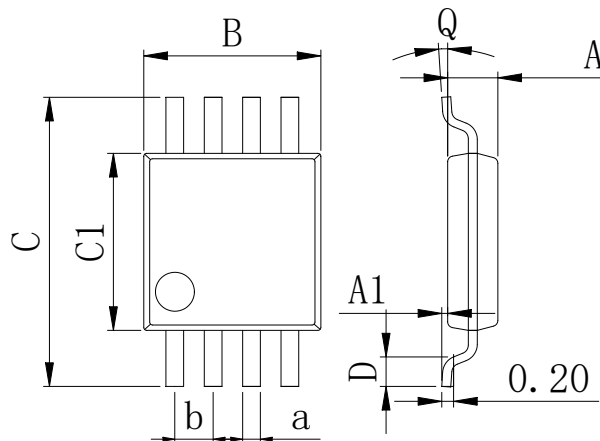
### TSSOP-8 (4.4\*3.0)



| Dimensions In Millimeters(TSSOP-8) |      |      |      |      |      |      |    |      |          |
|------------------------------------|------|------|------|------|------|------|----|------|----------|
| Symbol:                            | A    | A1   | B    | C    | C1   | D    | Q  | a    | b        |
| Min:                               | 0.85 | 0.05 | 2.90 | 6.20 | 4.30 | 0.40 | 0° | 0.20 | 0.65 BSC |
| Max:                               | 0.95 | 0.20 | 3.10 | 6.60 | 4.50 | 0.80 | 8° | 0.25 |          |

**Physical Dimensions**
**SOP-8**


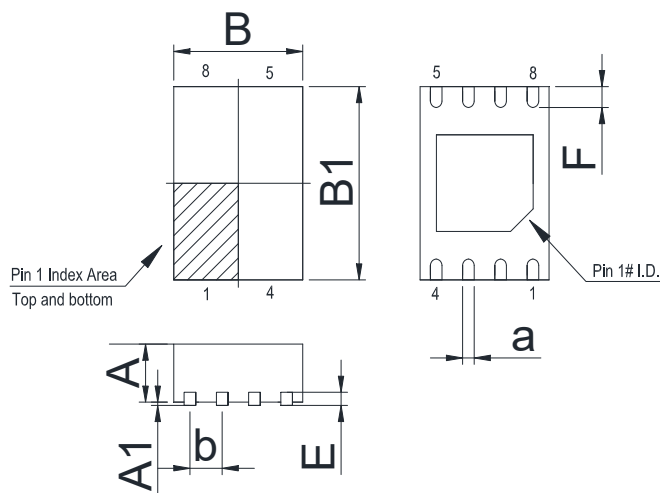
| Dimensions In Millimeters(SOP-8) |      |      |      |      |      |      |    |      |          |
|----------------------------------|------|------|------|------|------|------|----|------|----------|
| Symbol:                          | A    | A1   | B    | C    | C1   | D    | Q  | a    | b        |
| Min:                             | 1.35 | 0.05 | 4.90 | 5.80 | 3.80 | 0.40 | 0° | 0.35 | 1.27 BSC |
| Max:                             | 1.55 | 0.20 | 5.10 | 6.20 | 4.00 | 0.80 | 8° | 0.45 |          |

**MSOP-8**


| Dimensions In Millimeters(MSOP-8) |      |      |      |      |      |      |    |      |          |
|-----------------------------------|------|------|------|------|------|------|----|------|----------|
| Symbol:                           | A    | A1   | B    | C    | C1   | D    | Q  | a    | b        |
| Min:                              | 0.80 | 0.05 | 2.90 | 4.75 | 2.90 | 0.35 | 0° | 0.25 | 0.65 BSC |
| Max:                              | 0.90 | 0.20 | 3.10 | 5.05 | 3.10 | 0.75 | 8° | 0.35 |          |

**Physical Dimensions**

DFN-8 2\*3



| Dimensions In Millimeters(DFN-8 2*3) |      |      |      |      |      |      |      |         |
|--------------------------------------|------|------|------|------|------|------|------|---------|
| Symbol:                              | A    | A1   | B    | B1   | E    | F    | a    | b       |
| Min:                                 | 0.85 | 0    | 1.90 | 2.90 | 0.15 | 0.25 | 0.20 | 0.50TYP |
| Max:                                 | 0.95 | 0.05 | 2.10 | 3.10 | 0.25 | 0.35 | 0.30 |         |

## Revision History

| DATE      | REVISION  | PAGE     |
|-----------|---|----------|
| 2016-12-7 | New   | 1-16     |
| 2023-8-31 | Update encapsulation type、 Update Lead Temperature、 Updated DIP-8 dimension | 1、 8、 12 |

**IMPORTANT STATEMENT:**

Huaguan Semiconductor reserves the right to change its products and services without notice. Before ordering, the customer shall obtain the latest relevant information and verify whether the information is up to date and complete. Huaguan Semiconductor does not assume any responsibility or obligation for the altered documents.

Customers are responsible for complying with safety standards and taking safety measures when using Huaguan Semiconductor products for system design and machine manufacturing. You will bear all the following responsibilities: Select the appropriate Huaguan Semiconductor products for your application; Design, validate and test your application; Ensure that your application meets the appropriate standards and any other safety, security or other requirements. To avoid the occurrence of potential risks that may lead to personal injury or property loss.

Huaguan Semiconductor products have not been approved for applications in life support, military, aerospace and other fields, and Huaguan Semiconductor will not bear the consequences caused by the application of products in these fields. All problems, responsibilities and losses arising from the user's use beyond the applicable area of the product shall be borne by the user and have nothing to do with Huaguan Semiconductor, and the user shall not claim any compensation liability against Huaguan Semiconductor by the terms of this Agreement.

The technical and reliability data (including data sheets), design resources (including reference designs), application or other design suggestions, network tools, safety information and other resources provided for the performance of semiconductor products produced by Huaguan Semiconductor are not guaranteed to be free from defects and no warranty, express or implied, is made. The use of testing and other quality control technologies is limited to the quality assurance scope of Huaguan Semiconductor. Not all parameters of each device need to be tested.

The documentation of Huaguan Semiconductor authorizes you to use these resources only for developing the application of the product described in this document. You have no right to use any other Huaguan Semiconductor intellectual property rights or any third party intellectual property rights. It is strictly forbidden to make other copies or displays of these resources. You should fully compensate Huaguan Semiconductor and its agents for any claims, damages, costs, losses and debts caused by the use of these resources. Huaguan Semiconductor accepts no liability for any loss or damage caused by infringement.



单击下面可查看定价，库存，交付和生命周期等信息

[>>HGSEMI\(华冠\)](#)